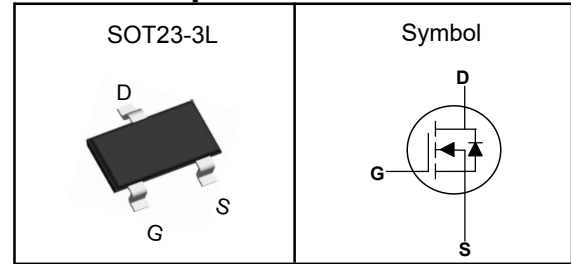


N-Channel Enhancement Mode MOSFET

Features

- Low $R_{ds(on)}$ for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	20	V
$R_{DS(ON)-Typ}$	10	m Ω
I_D	6	A

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	30	A
I_D	Continuous Drain Current	6	A
P_D	Maximum Power Dissipation	1.4	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	100	$^\circ\text{C/W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.



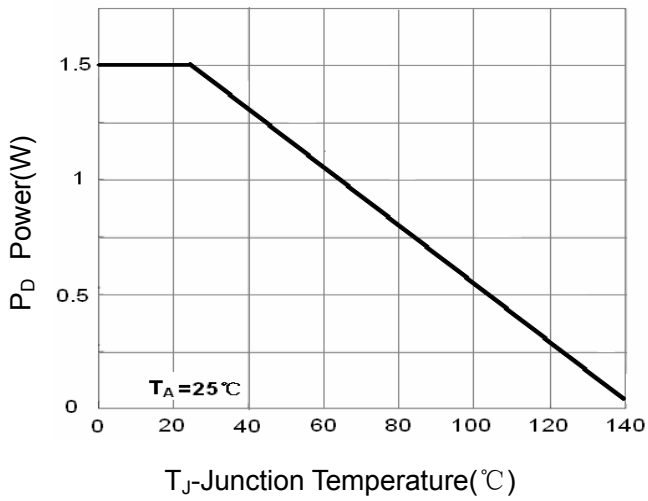
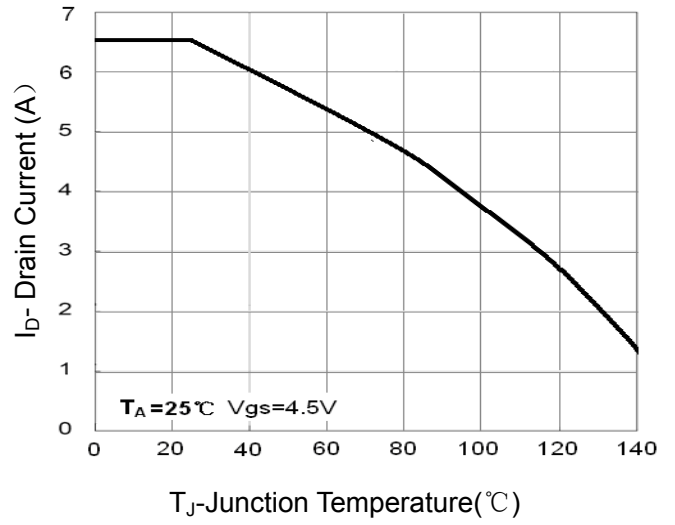
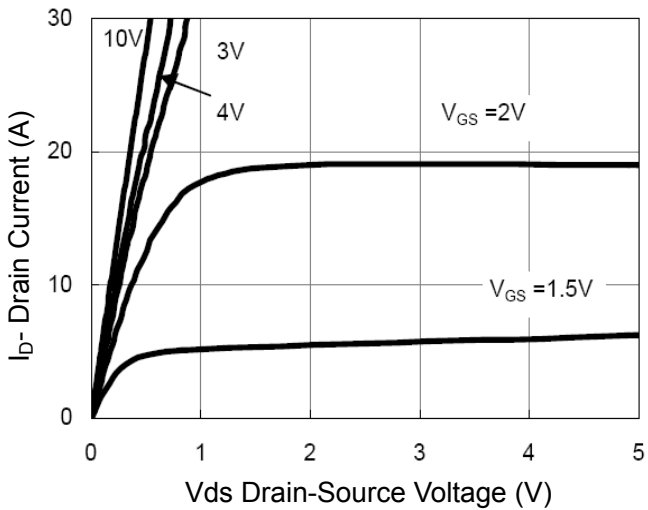
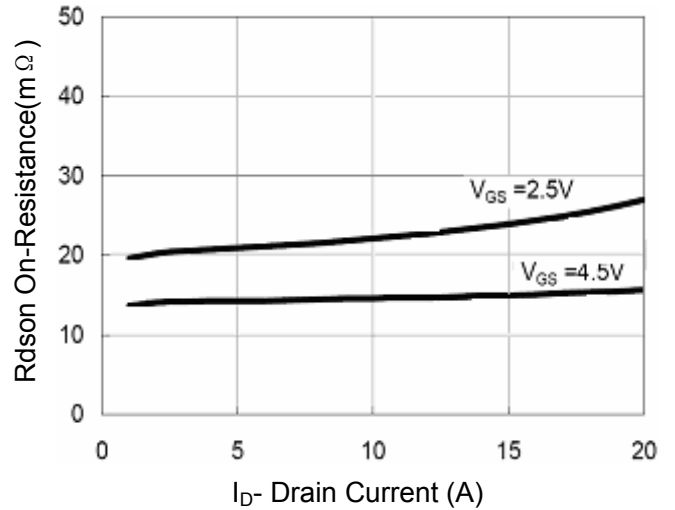
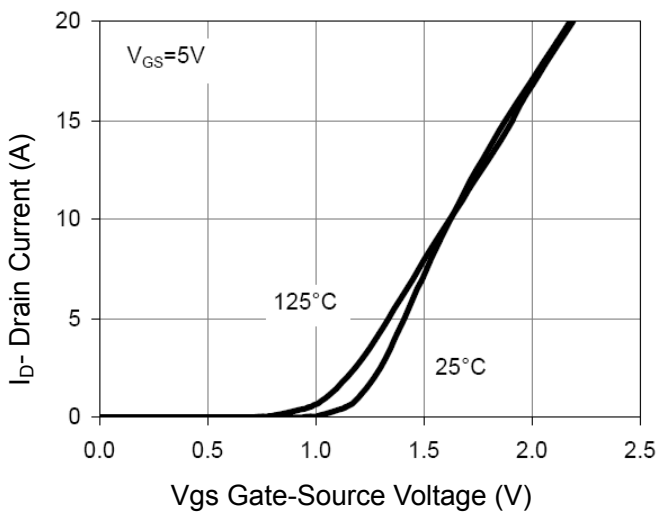
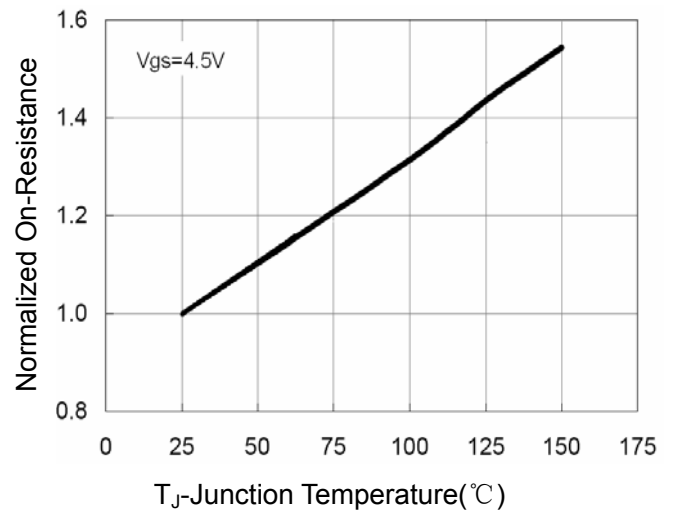
N-Channel Enhancement Mode MOSFET

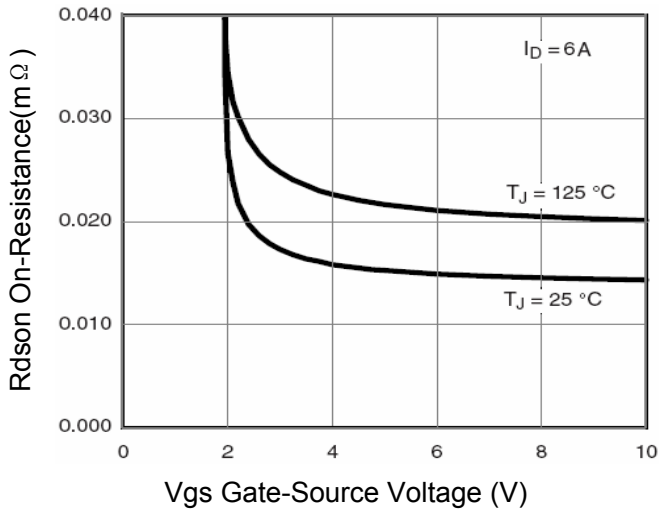
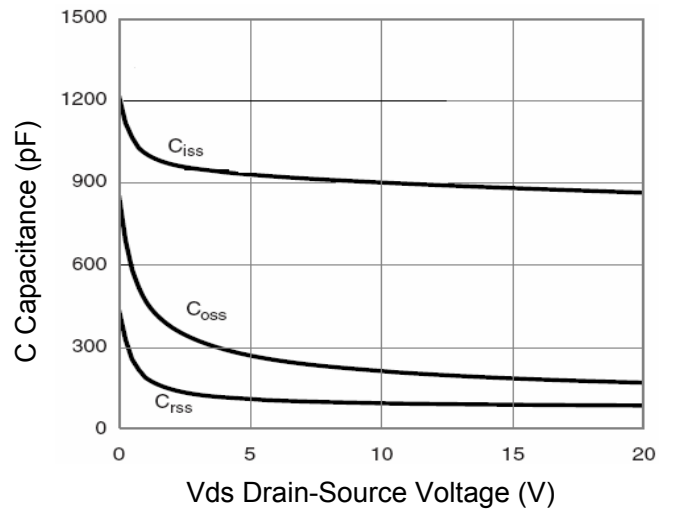
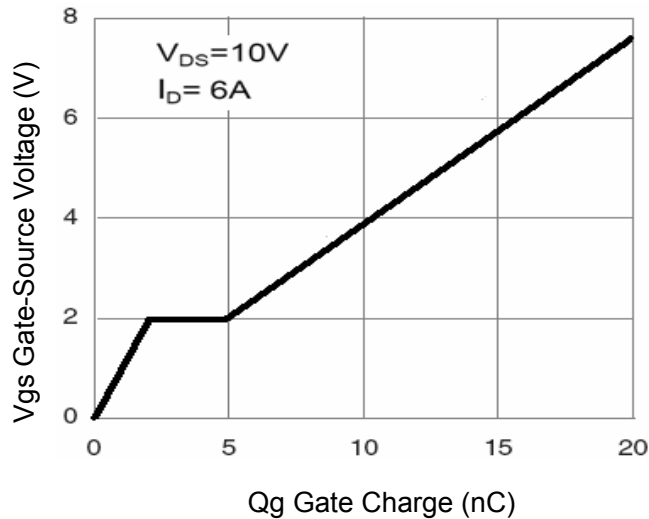
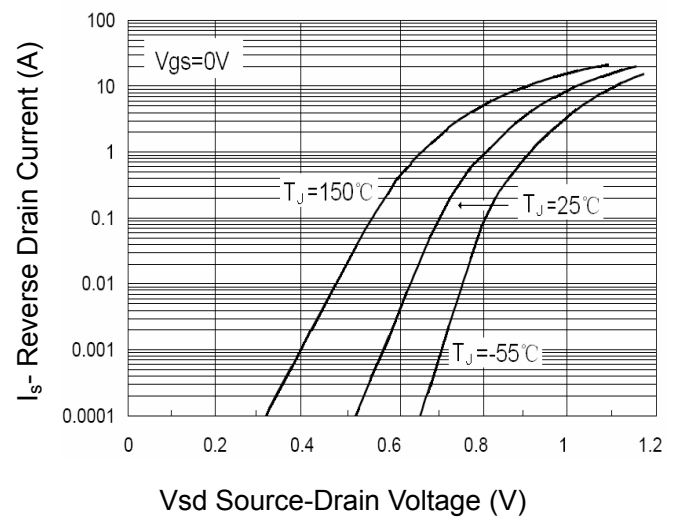
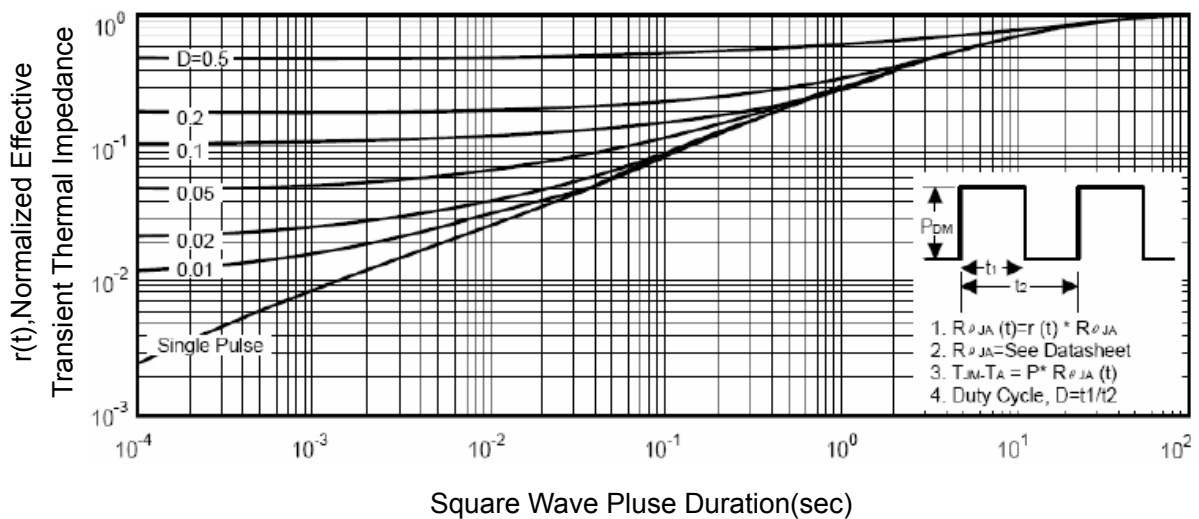
Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

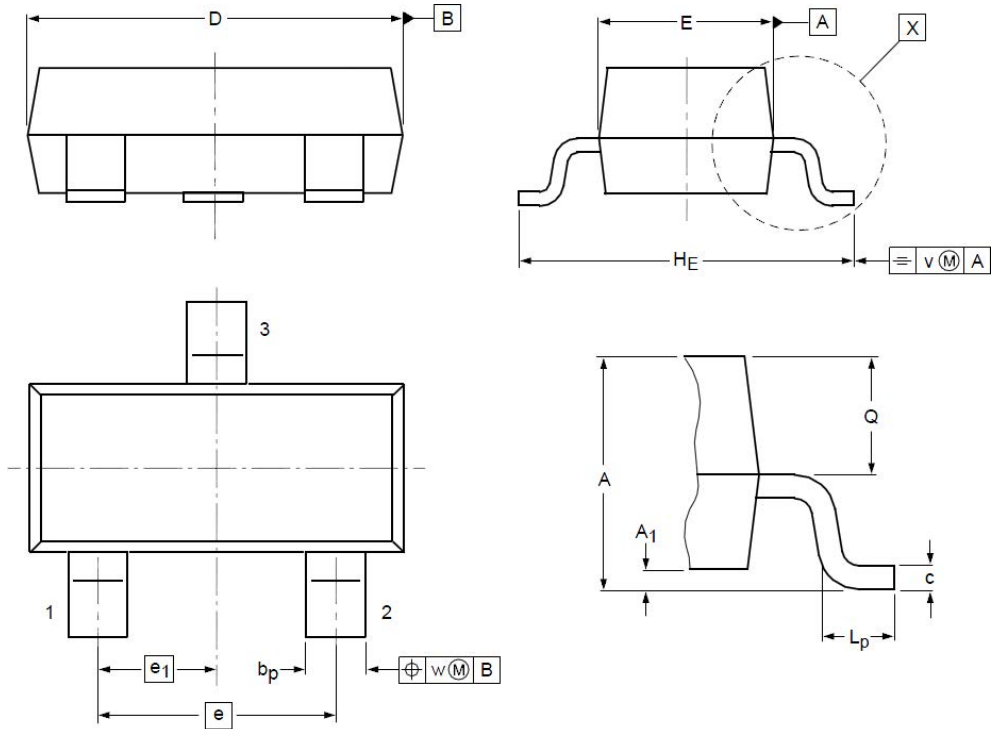
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$	---	---	1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	---	0.9	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=4.5V, I_D=6A$	---	10	13	$m\Omega$
		$V_{GS}=2.5V, I_D=5.5A$	---	14	18	$m\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=10V, \text{Freq.}=1\text{MHz}$	---	900	---	pF
C_{oss}	Output Capacitance		---	220	---	
C_{rss}	Reverse Transfer Capacitance		---	100	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=10V, I_D=6A, V_{GS}=4.5V, R_G=6\Omega$	---	10	---	nS
T_r	Turn-on Rise Time		---	11	---	
$T_{d(off)}$	Turn-off Delay Time		---	35	---	
T_f	Turn-off Fall Time		---	30	---	
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=6A$	---	10	---	S
Q_g	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V, I_D=6A$	---	12	---	nC
Q_{gs}	Gate-Source Charge		---	2.3	---	
Q_{gd}	Gate-Drain Charge		---	1	---	
Source-Drain Characteristics ($T_J=25^{\circ}\text{C}$)						
$V_{SD}^{④}$	Diode Forward Voltage	$I_S=6A, V_{GS}=0V$	---	---	1.2	V

Note ④ : Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET
Typical Characteristics

Figure 1 Power Dissipation

Figure 2 Drain Current

Figure 3 Output Characteristics

Figure 4 Drain-Source On-Resistance

Figure 5 Transfer Characteristics

Figure 6 Drain-Source On-Resistance

N-Channel Enhancement Mode MOSFET

Figure 7 Rdson vs Vgs

Figure 8 Capacitance vs Vds

Figure 9 Gate Charge

Figure 10 Source-Drain Diode Forward

Figure 11 Normalized Maximum Transient Thermal Impedance

N-Channel Enhancement Mode MOSFET
SOT23-3L Package Outline Dimensions


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.25	e₁	--	0.95	--
A₁	0.01	0.05	0.10	H_E	2.50	2.80	3.00
b_p	0.30	0.40	0.50	L_P	0.30	0.45	0.60
c	0.10	0.15	0.20	Q	0.23	0.28	0.33
D	2.70	2.90	3.10	V	--	0.20	--
E	1.40	1.55	1.75	W	--	0.20	--
e	--	1.90	--				